

ON Semiconductor			9/20/2020	
Base Part		NCV8164	HF	Pb-free
Orderable Part		NCV8164ASN330T1G	Total weight (mg)	14.08
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.42	Silicon (Si)	7440-21-3	100
Die Attach	0.11	Silver (Ag)	7440-22-4	80
		Phenolic Resin-2	54208-63-8	20
Lead Frame	5.78	Silver (Ag)	7440-22-4	1.22
		Zinc (Zn)	7440-66-6	0.12
		Iron (Fe)	7439-89-6	2.35
		Copper (Cu)	7440-50-8	96.28
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	7.34	Phenolic Resin	proprietary	5
		Ortho Cresol Novolac Resin	29690-82-2	2
		Epoxy Phenol Resin	proprietary	5
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	87.5
Plating	0.39	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.04	Gold (Au)	7440-57-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				